HERD STK/SCD group meeting

实验物理中心/天体物理中心

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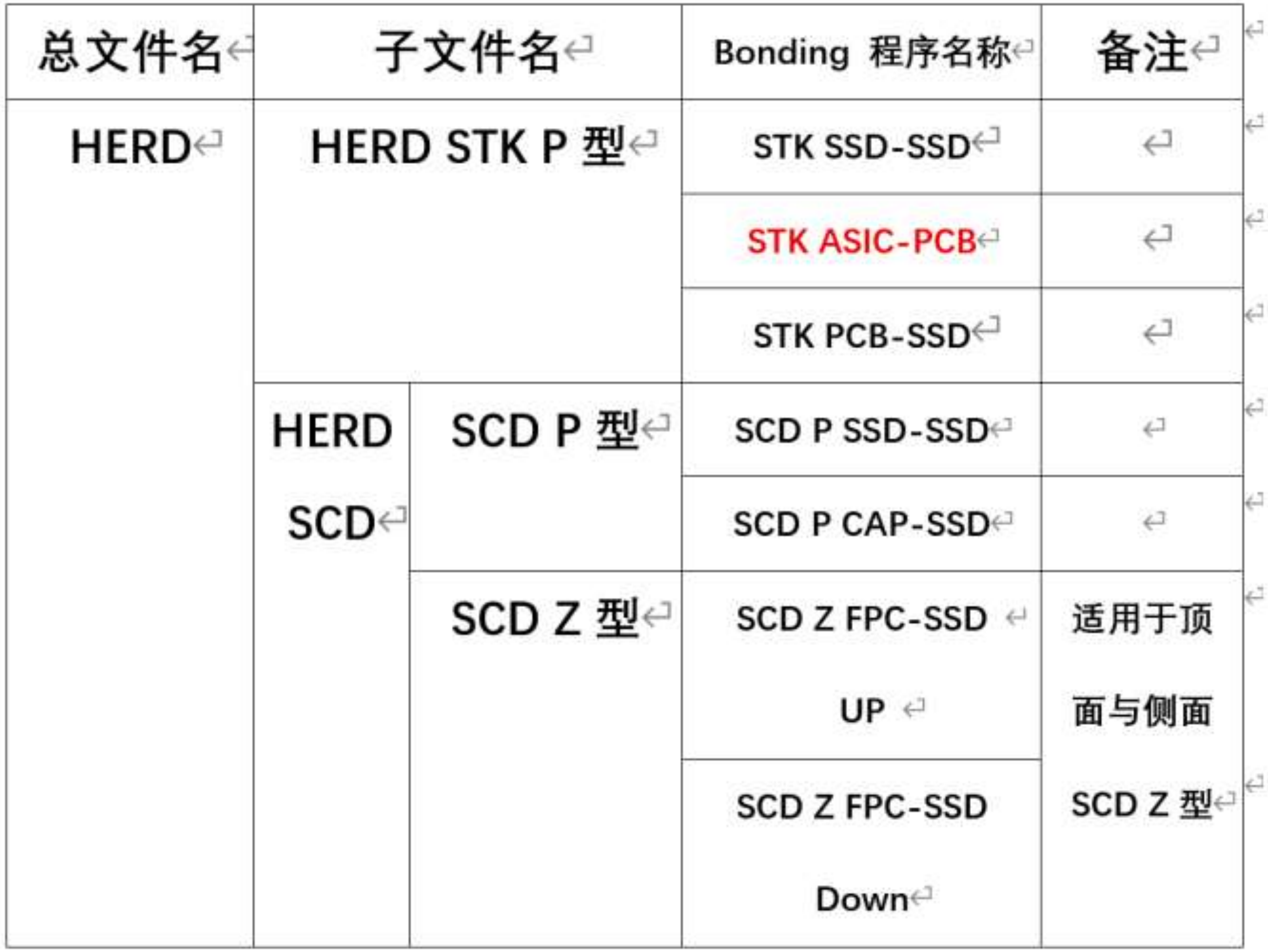
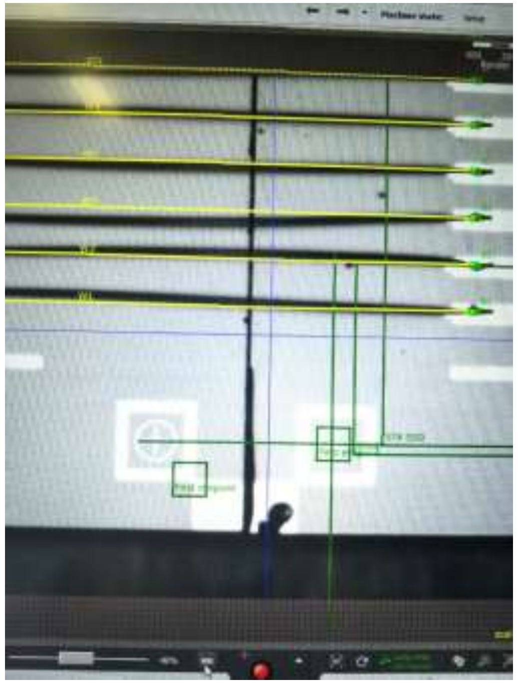
HERD STK/SCD bonding技术文档

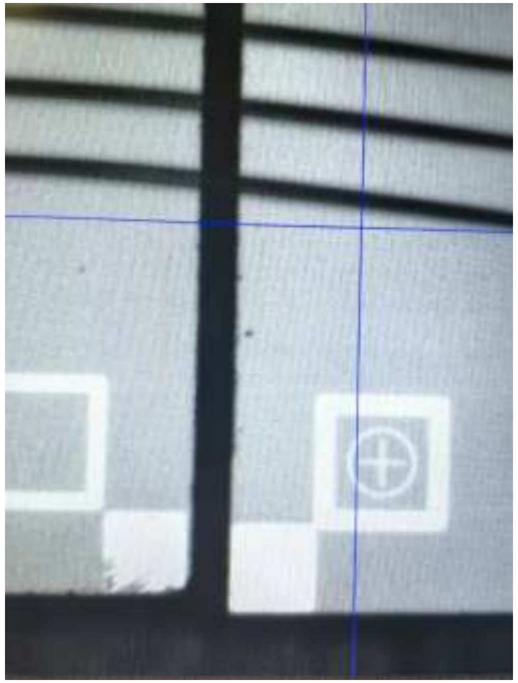


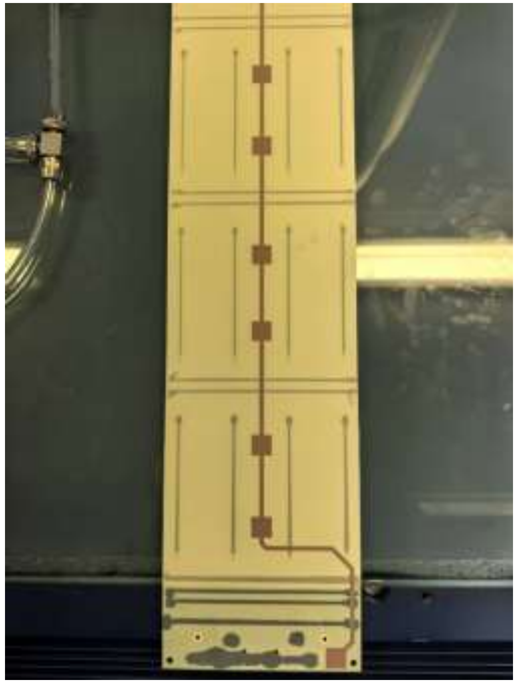
总文件名	子文件名		Bonding 程序名称	备注
HERD	HERD STK P 型		STK SSD-SSD	
			STK ASIC-PCB	
			STK PCB-SSD	
	HERD SCD	SCD P 型	SCD P SSD-SSD	
			SCD P CAP-SSD	
		SCD Z 型	SCD Z FPC-SSD UP	适用于顶面与侧面 SCD Z 型
			SCD Z FPC-SSD Down	

- 新增STK ASIC-PCB 键合程序，并完成两板TFH 键合

STK dummy ladder

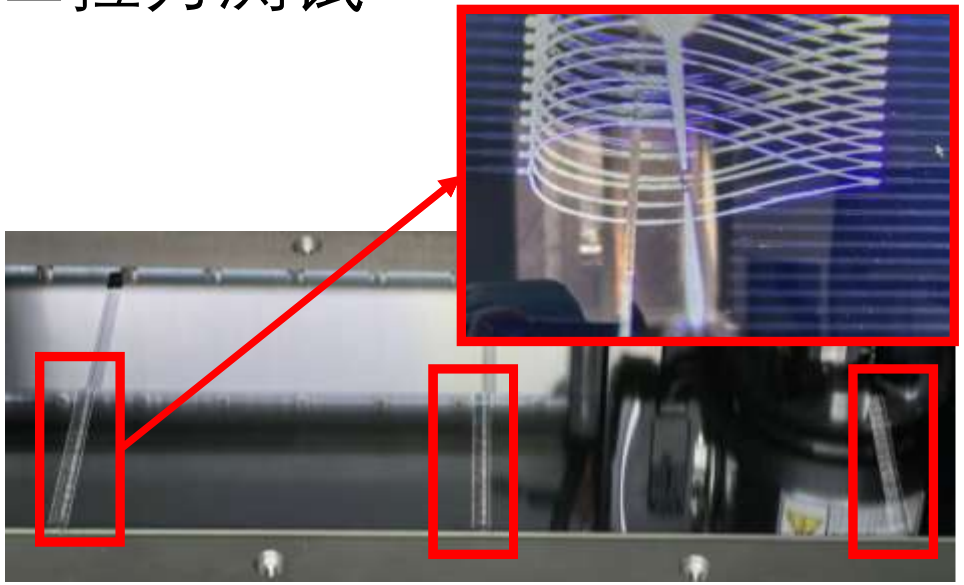


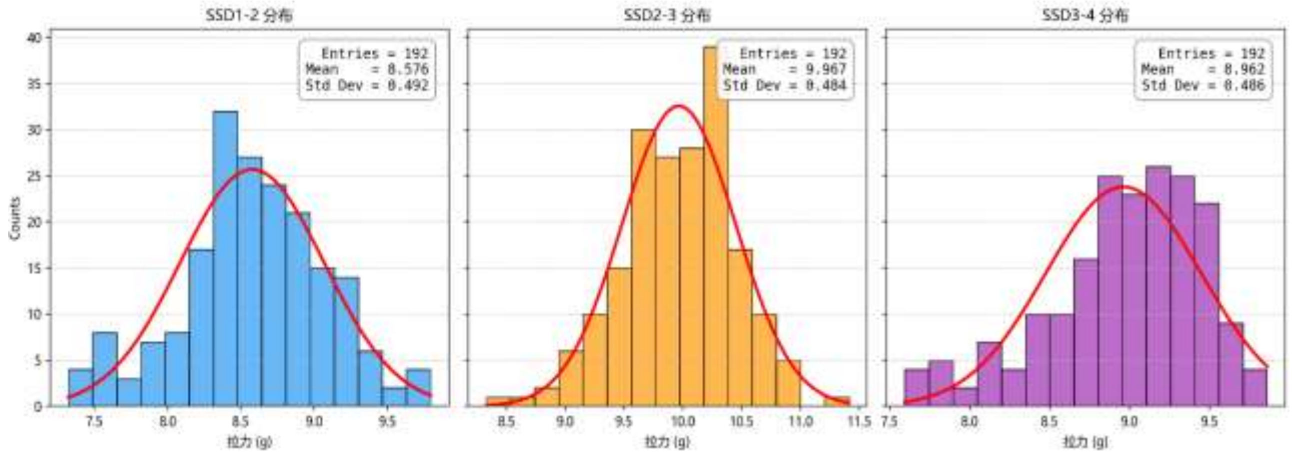


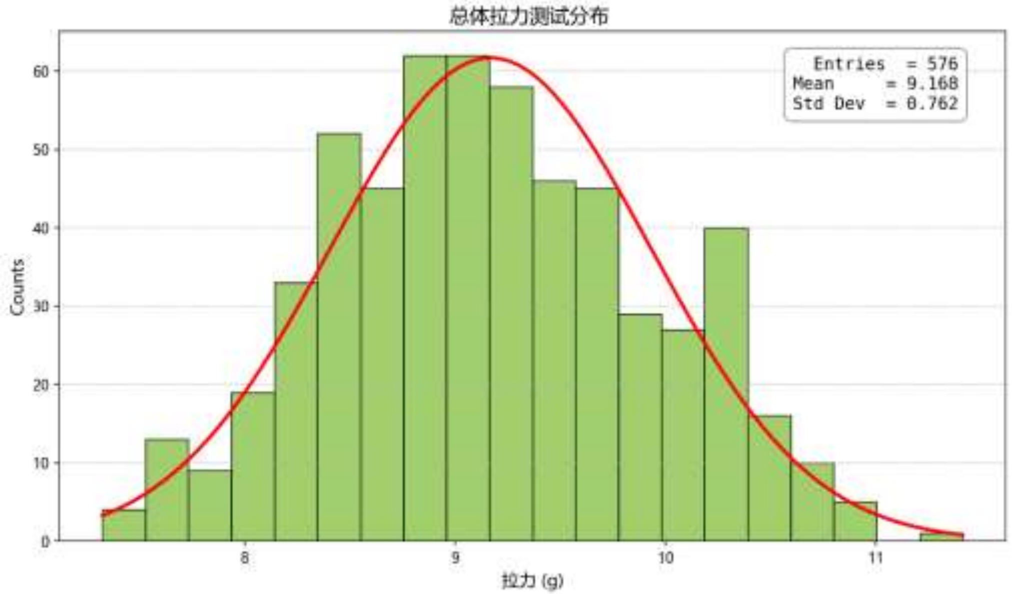


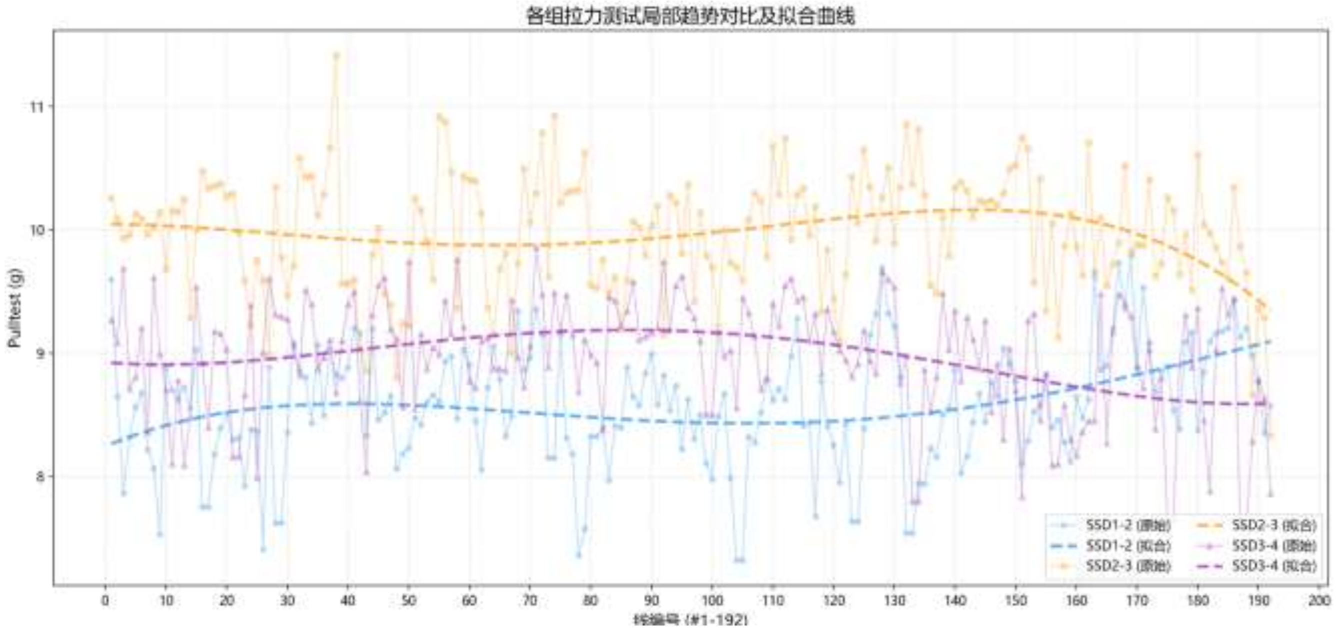
- 芯片SSD-SSD粘贴未对齐
- 芯片胶水未压实（后续发现是工装翘曲导致）

□拉力测试




SSD1-2 分布
Entries = 192
Mean = 8.576
Std Dev = 0.492
SSD2-3 分布
Entries = 192
Mean = 9.967
Std Dev = 0.484
SSD3-4 分布
Entries = 192
Mean = 8.962
Std Dev = 0.486
Counts
0
5
10
15
20
25
30
35
40
7.5
8.0
8.5
9.0
9.5
10.0
10.5
11.0
11.5
拉力 (g)


总体拉力测试分布
Entries = 576
Mean = 9.168
Std Dev = 0.762
Counts
0
10
20
30
40
50
60
8
9
10
11
拉力 (g)


各组拉力测试局部趋势对比及拟合曲线
Pulltest (g)
8
9
10
11
0
10
20
30
40
50
60
70
80
90
100
110
120
130
140
150
160
170
180
190
200
线编号 (#1-192)
SSD1-2 (原始)
SSD1-2 (拟合)
SSD2-3 (原始)
SSD2-3 (拟合)
SSD3-4 (原始)
SSD3-4 (拟合)

Thanks for your attention